

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method for a three-dimensional structural body, comprising:

A. holding, by a first holding member, a first cross-sectional form member from amongst a plurality of cross-sectional form members above a first substrate;

~~_____ sequentially~~ B. first bonding/transferring and laminating the first cross-sectional form member a plurality of cross-sectional form members onto a second substrate; each cross-sectional form member being held in space above a first substrate by a holding member; and

C. releasing the first cross-sectional form member from the first holding member after the first bonding/transferring and laminating; laminating

_____ D. holding, by a second holding member, a second cross-sectional form member from amongst the plurality of cross-sectional form members above the first substrate;

_____ E. second bonding/transferring and laminating the second cross-sectional form member onto the first cross-sectional form member;

_____ F. releasing the second cross-sectional form member from the second holding member after the second bonding/transferring and laminating;

_____ Repeating steps D, E and F, at least once, wherein, for each repetition, the "second holding member" and "second cross-sectional form member" becomes a new cross-sectional form member from amongst the plurality of cross-sectional form members and the "first cross-sectional form member" becomes the second cross-sectional form member from a previous repetition, respectively, wherein

each cross-sectional form member corresponds to a slice pattern of the three-dimensional structural body.

2. (Currently Amended) The manufacturing method according to claim 1, wherein the first or second bonding/transferring and laminating is performed using surface-activated bonding.

3. (Currently Amended) The manufacturing method according to claim 1, wherein the first or second holding member comprises a coupling member connected to a cross-sectional form member, and a frame member, wherein the first substrate is connected to the coupling member through the frame member.

4. (Original) The manufacturing method according to claim 3, wherein the frame member includes a columnar part provided on the first substrate, and a frame part provided on the columnar part and connected to the coupling member.

5. (Previously Presented) The manufacturing method according to claim 4, further comprising:

laminating a sacrificial layer and a material layer on the first substrate;

forming the cross-sectional form members, the frame part and the coupling member in the material layer; and

removing the sacrificial layer while a portion becoming the columnar part remains, and a gap occurs at least between the cross-sectional form members and the first substrate.

6. (Currently Amended) The manufacturing method according to claim 5, wherein the plurality of cross-sectional form members are formed by using a lithography method.

7. (Original) The manufacturing method according to claim 5, wherein the sacrificial layer is removed by using an under etching method.

8. (Currently Amended) The manufacturing method according to claim 3, wherein the coupling member is ruptured at a time of the first or second bonding/transferring and laminating.

9. (Currently Amended) The manufacturing method according to claim 1, further comprising a collective of one or more cross-sectional form members, wherein the first or second bonding/transferring and laminating is performed by causing the collective of cross-sectional form members to face the second substrate, and by sandwiching the collective of cross-sectional form members between the first substrate and the second substrate.

10. (Currently Amended) The manufacturing method according to claim 3, further comprising a collective of one or more cross-sectional form members, wherein the first or second bonding/transferring and laminating is performed by causing the collective of cross-sectional form members to face the second substrate, and by sandwiching the collective of cross-sectional form members between the first substrate and the second substrate, and the coupling member is ruptured after the collective of cross-sectional form members are transferred on the second substrate and when the second substrate is separated from the first substrate.

11. (Previously Presented) The manufacturing method according to claim 9, wherein a surface on the first substrate facing the collective of cross-sectional form members is flat.

12. (Previously Presented) The manufacturing method according to claim 10, wherein a surface on the first substrate facing the collective of cross-sectional form members is flat.

13. (Previously Presented) The manufacturing method according to claim 9, wherein a pressure to sandwich the collective of cross-sectional form members between the

first substrate and the second substrate is applied to all of the cross-sectional form members of the collective.

14. (Previously Presented) The manufacturing method according to claim 10, wherein a pressure to sandwich the collective of cross-sectional form members between the first substrate and the second substrate is applied to all of the cross-sectional form members of the collective.

15. (Currently Amended) The manufacturing method according to claim 1, wherein the first or second holding member comprises a first frame member positioned on the first substrate, a second frame member provided inside of the first frame member, a first coupling member connected to a cross-sectional form member, and a second coupling member connecting the first and the second frame members.

16. (Previously Presented) The manufacturing method according to claim 15, wherein the second frame member and a plurality of cross-sectional form members connected to the second frame member are simultaneously bonded and transferred onto the second substrate.

17. (Currently Amended) The manufacturing method according to claim 16, wherein the first and second bonding/transferring and laminating is performed by causing the second substrate and the plurality of cross-sectional form members connected to the second frame member to face each other, and by sandwiching the second frame member and the plurality of cross-sectional form members between the first substrate and the second substrate.

18. (Original) The manufacturing method according to claim 1, wherein the three-dimensional structural body includes a photonic crystal having a periodic structure.

19. (New) A manufacturing method for a three-dimensional structural body, comprising:

sequentially bonding/transferring and laminating a plurality of cross-sectional form members onto a second substrate, each cross-sectional form member being held in space above a first substrate by a holding member; and

releasing the cross-sectional form member from the holding member after the bonding/transferring and laminating, wherein

the bonding/transferring and laminating is performed using surface-activated bonding.

20. (New) A manufacturing method for a three-dimensional structural body, comprising:

sequentially bonding/transferring and laminating a plurality of cross-sectional form members onto a second substrate, each cross-sectional form member being held in space above a first substrate by a holding member; and

releasing the cross-sectional form member from the holding member after the bonding/transferring and laminating, wherein

the holding member comprises a coupling member connected to a cross-sectional form member, and a frame member, wherein

the first substrate is connected to the coupling member through the frame member, wherein

the frame member includes a columnar part provided on the first substrate, and a frame part provided on the columnar part and connected to the coupling member;

the manufacturing method further comprising:

laminating a sacrificial layer and a material layer on the first substrate;

forming the cross-sectional form members, the frame part and the coupling member in the material layer; and

removing the sacrificial layer while a portion becoming the columnar part remains, and a gap occurs at least between the cross-sectional form members and the first substrate.